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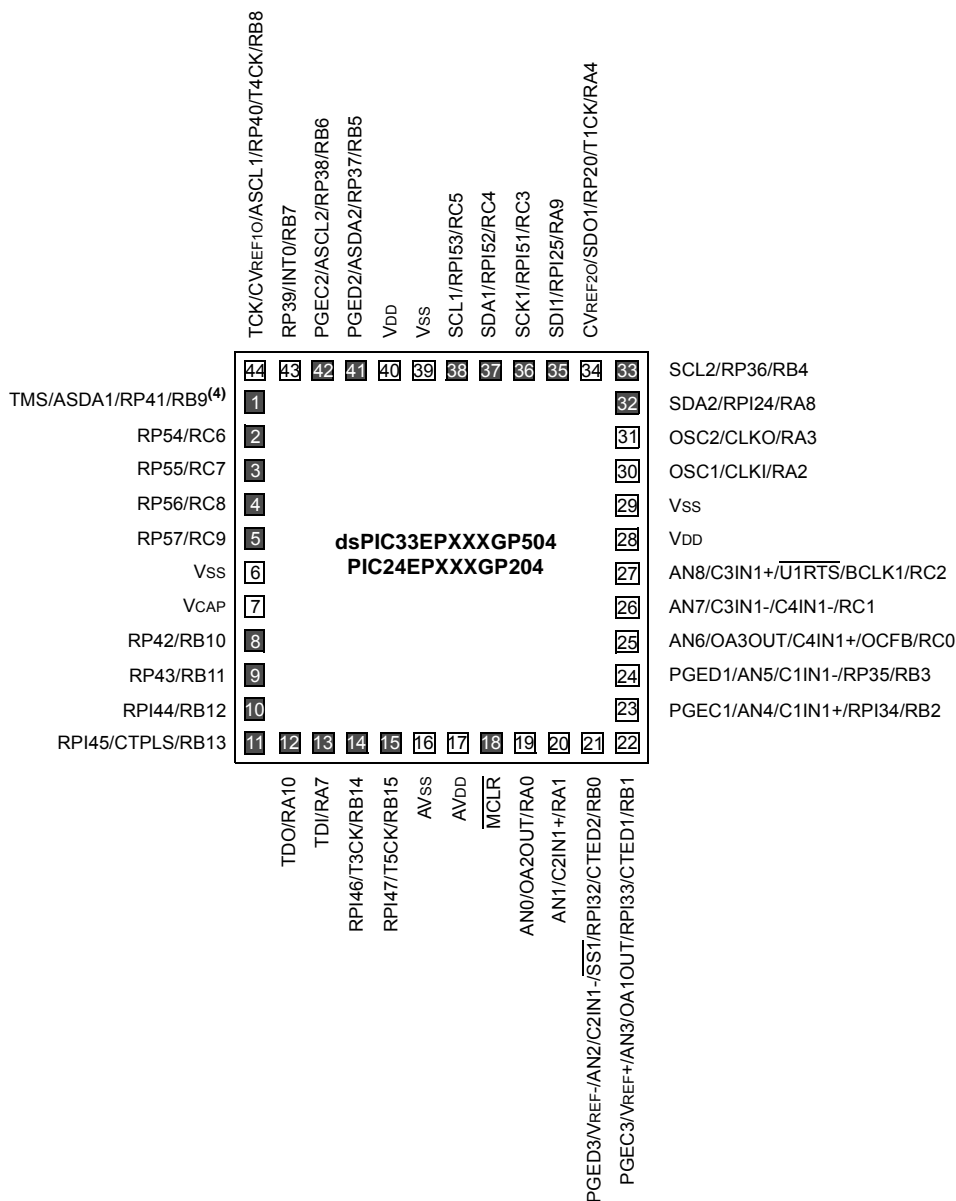
Details

Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPS
Connectivity	I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep512mc204t-i-ml

Pin Diagrams (Continued)

44-Pin VTLA^(1,2,3)

■ = Pins are up to 5V tolerant

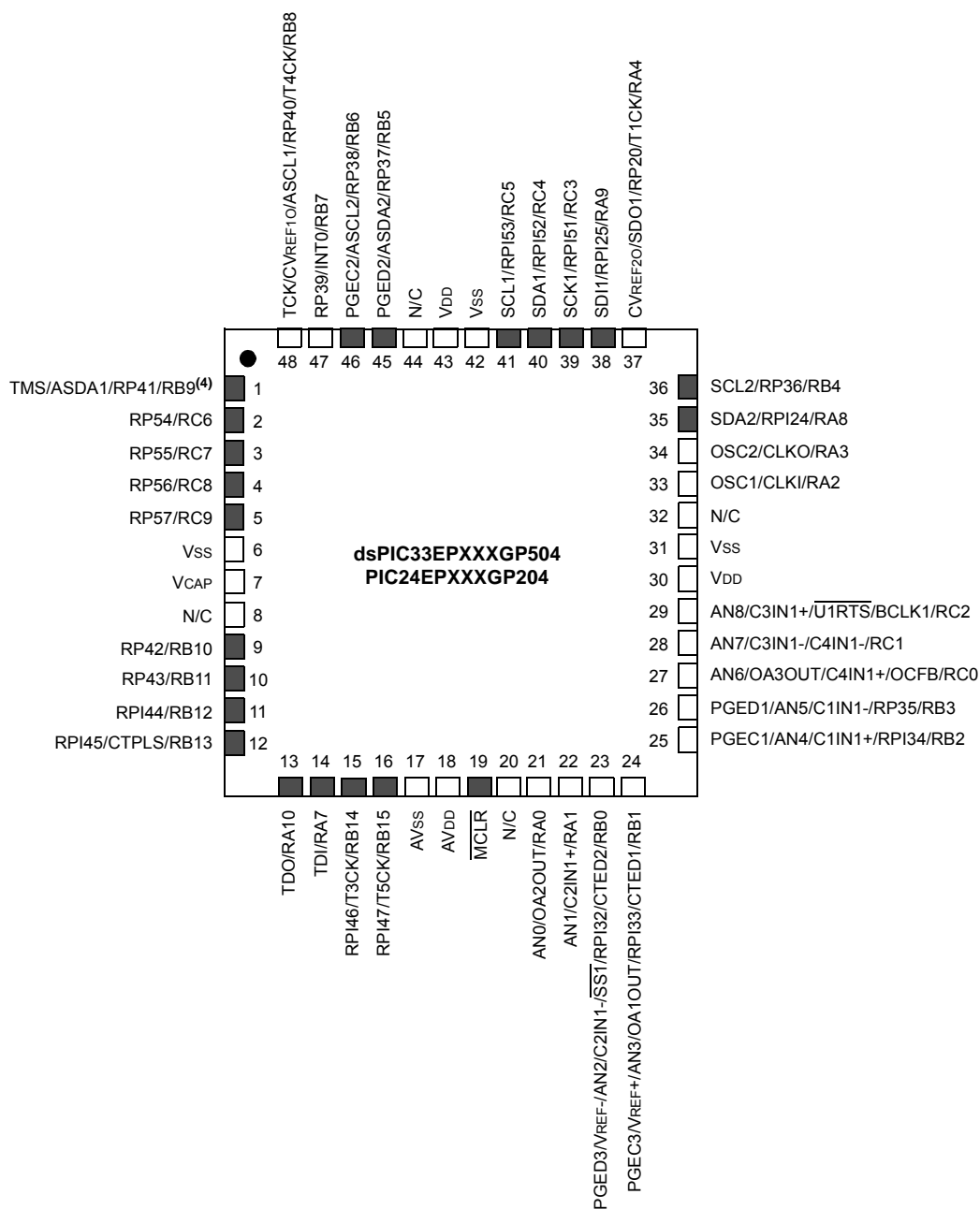


- Note 1:** The RPN/RPIN pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.
- Note 2:** Every I/O port pin (RAX-RGX) can be used as a Change Notification pin (CNAX-CNGX). See **Section 11.0 “I/O Ports”** for more information.
- Note 3:** The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.
- Note 4:** There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

Pin Diagrams (Continued)

48-Pin UQFN^(1,2,3)

■ = Pins are up to 5V tolerant



- Note**
- 1: The RPN/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.
 - 2: Every I/O port pin (RAX-RGx) can be used as a Change Notification pin (CNAX-CNGx). See **Section 11.0 “I/O Ports”** for more information.
 - 3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.
 - 4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to “**CPU**” (DS70359) in the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).

- 2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for digital signal processing. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space.

An instruction prefetch mechanism helps maintain throughput and provides predictable execution. Most instructions execute in a single-cycle effective execution rate, with the exception of instructions that change the program flow, the double-word move (MOV.D) instruction, PSV accesses and the table instructions. Overhead-free program loop constructs are supported using the DO and REPEAT instructions, both of which are interruptible at any point.

3.1 Registers

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices have sixteen, 16-bit working registers in the programmer's model. Each of the working registers can act as a data, address or address offset register. The 16th working register (W15) operates as a Software Stack Pointer for interrupts and calls.

3.2 Instruction Set

The instruction set for dsPIC33EPXXXGP50X and dsPIC33EPXXXMC20X/50X devices has two classes of instructions: the MCU class of instructions and the DSP class of instructions. The instruction set for PIC24EPXXXGP/MC20X devices has the MCU class of instructions only and does not support DSP instructions. These two instruction classes are seamlessly integrated into the architecture and execute from a single execution unit. The instruction set includes many addressing modes and was designed for optimum C compiler efficiency.

3.3 Data Space Addressing

The base Data Space can be addressed as 64 Kbytes (32K words).

The Data Space includes two ranges of memory, referred to as X and Y data memory. Each memory range is accessible through its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear Data Space. On dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y Data Spaces have memory locations that are device-specific, and are described further in the data memory maps in **Section 4.2 “Data Address Space”**.

The upper 32 Kbytes of the Data Space memory map can optionally be mapped into Program Space (PS) at any 32-Kbyte aligned program word boundary. The Program-to-Data Space mapping feature, known as Program Space Visibility (PSV), lets any instruction access Program Space as if it were Data Space. Moreover, the Base Data Space address is used in conjunction with a Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space (EDS) address. The EDS can be addressed as 8M words or 16 Mbytes. Refer to the “**Data Memory**” (DS70595) and “**Program Memory**” (DS70613) sections in the “*dsPIC33/PIC24 Family Reference Manual*” for more details on EDS, PSV and table accesses.

On the dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, overhead-free circular buffers (Modulo Addressing) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. The X AGU Circular Addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data re-ordering for radix-2 FFT algorithms. PIC24EPXXXGP/MC20X devices do not support Modulo and Bit-Reversed Addressing.

3.4 Addressing Modes

The CPU supports these addressing modes:

- Inherent (no operand)
- Relative
- Literal
- Memory Direct
- Register Direct
- Register Indirect

Each instruction is associated with a predefined addressing mode group, depending upon its functional requirements. As many as six addressing modes are supported for each instruction.

4.2 Data Address Space

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X CPU has a separate 16-bit-wide data memory space. The Data Space is accessed using separate Address Generation Units (AGUs) for read and write operations. The data memory maps, which are presented by device family and memory size, are shown in Figure 4-7 through Figure 4-16.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the Data Space. This arrangement gives a base Data Space address range of 64 Kbytes (32K words).

The base Data Space address is used in conjunction with a Read or Write Page register (DSRPAG or DSWPAG) to form an Extended Data Space, which has a total address range of 16 Mbytes.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices implement up to 52 Kbytes of data memory (4 Kbytes of data memory for Special Function Registers and up to 48 Kbytes of data memory for RAM). If an EA points to a location outside of this area, an all-zero word or byte is returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte-addressable, 16-bit-wide blocks. Data is aligned in data memory and registers as 16-bit words, but all Data Space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® MCU devices and improve Data Space memory usage efficiency, the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X instruction set supports both word and byte operations. As a consequence of byte accessibility, all Effective Address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] results in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

A data byte read, reads the complete word that contains the byte, using the LSB of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, data memory and registers are organized as two parallel, byte-wide entities with shared (word) address decode but separate write lines. Data byte writes only write to the corresponding side of the array or register that matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction underway is completed. If the error occurred on a write, the instruction is executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user application to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB. The MSB is not modified.

A Sign-Extend (SE) instruction is provided to allow user applications to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, user applications can clear the MSB of any W register by executing a Zero-Extend (ZE) instruction on the appropriate address.

4.2.3 SFR SPACE

The first 4 Kbytes of the Near Data Space, from 0x0000 to 0x0FFF, is primarily occupied by Special Function Registers (SFRs). These are used by the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'.

Note: The actual set of peripheral features and interrupts varies by the device. Refer to the corresponding device tables and pinout diagrams for device-specific information.

4.2.4 NEAR DATA SPACE

The 8-Kbyte area, between 0x0000 and 0x1FFF, is referred to as the Near Data Space. Locations in this space are directly addressable through a 13-bit absolute address field within all memory direct instructions. Additionally, the whole Data Space is addressable using MOV instructions, which support Memory Direct Addressing mode with a 16-bit address field, or by using Indirect Addressing mode using a working register as an Address Pointer.

FIGURE 4-14: DATA MEMORY MAP FOR PIC24EP128GP/MC20X/50X DEVICES

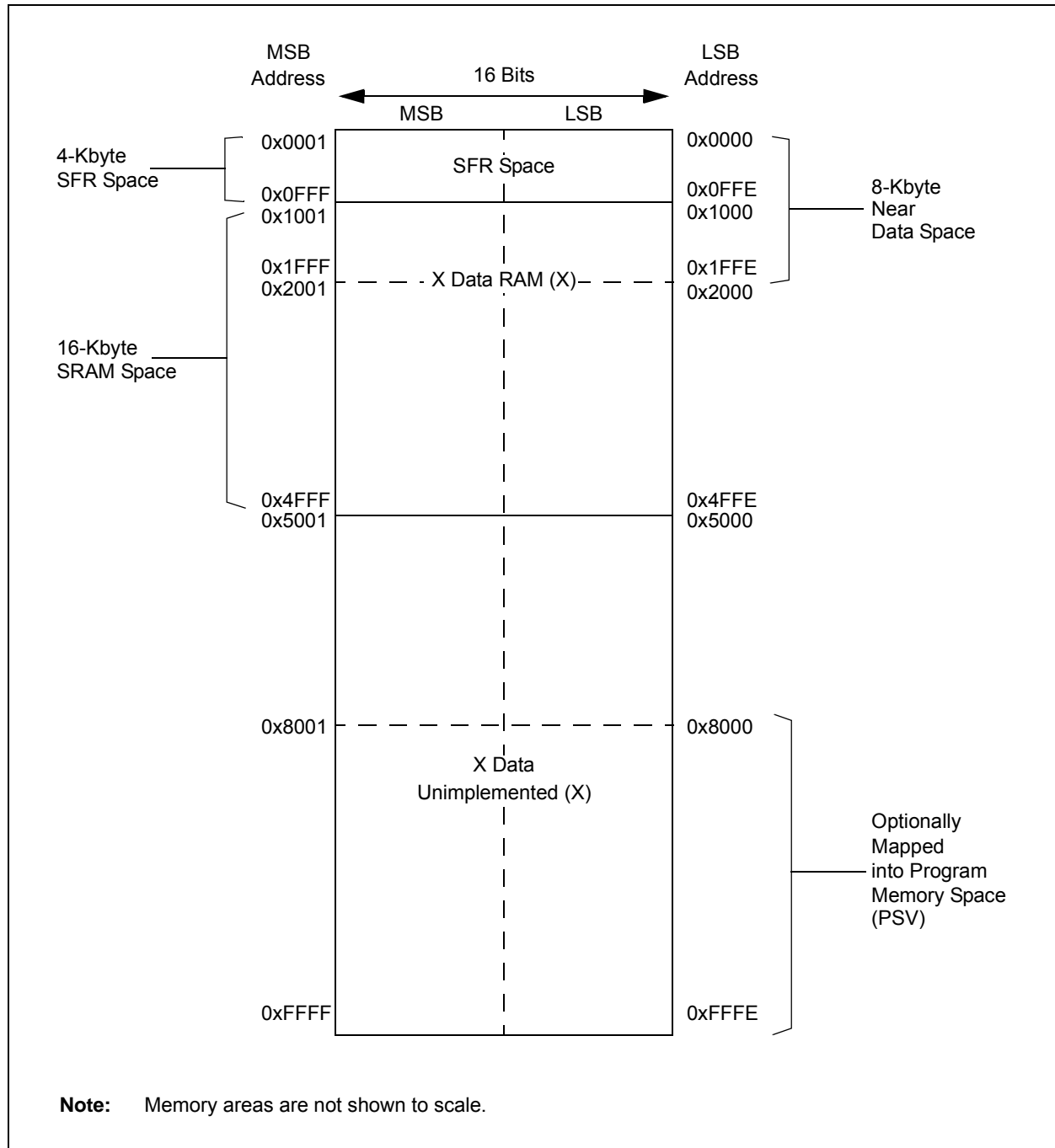


TABLE 4-6: INTERRUPT CONTROLLER REGISTER MAP FOR dsPIC33EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IFS0	0800	—	DMA1IF	AD1IF	U1TXIF	U1RXIF	SPI1IF	SPI1EIF	T3IF	T2IF	OC2IF	IC2IF	DMA0IF	T1IF	OC1IF	IC1IF	INT0IF	0000
IFS1	0802	U2TXIF	U2RXIF	INT2IF	T5IF	T4IF	OC4IF	OC3IF	DMA2IF	—	—	—	INT1IF	CNIF	CMIF	MI2C1IF	SI2C1IF	0000
IFS2	0804	—	—	—	—	—	—	—	—	—	IC4IF	IC3IF	DMA3IF	—	—	SPI2IF	SPI2EIF	0000
IFS3	0806	—	—	—	—	—	QE11IF	PSEMIF	—	—	—	—	—	—	MI2C2IF	SI2C2IF	—	0000
IFS4	0808	—	—	CTMUIF	—	—	—	—	—	—	—	—	—	CRCIF	U2EIF	U1EIF	—	0000
IFS5	080A	PWM2IF	PWM1IF	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IFS6	080C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IF	0000
IFS8	0810	JTAGIF	ICDIF	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IFS9	0812	—	—	—	—	—	—	—	—	—	PTG3IF	PTG2IF	PTG1IF	PTG0IF	PTGWDTIF	PTGSTIEIF	—	0000
IEC0	0820	—	DMA1IE	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE	T2IE	OC2IE	IC2IE	DMA0IE	T1IE	OC1IE	IC1IE	INT0IE	0000
IEC1	0822	U2TXIE	U2RXIE	INT2IE	T5IE	T4IE	OC4IE	OC3IE	DMA2IE	—	—	—	INT1IE	CNIE	CMIE	MI2C1IE	SI2C1IE	0000
IEC2	0824	—	—	—	—	—	—	—	—	—	IC4IE	IC3IE	DMA3IE	—	—	SPI2IE	SPI2EIE	0000
IEC3	0826	—	—	—	—	—	QE11IE	PSEMIE	—	—	—	—	—	—	MI2C2IE	SI2C2IE	—	0000
IEC4	0828	—	—	CTMUIE	—	—	—	—	—	—	—	—	—	CRCIE	U2EIE	U1EIE	—	0000
IEC5	082A	PWM2IE	PWM1IE	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC6	082C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IE	0000
IEC8	0830	JTAGIE	ICDIE	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC9	0832	—	—	—	—	—	—	—	—	—	PTG3IE	PTG2IE	PTG1IE	PTG0IE	PTGWDTIE	PTGSTIEIE	—	0000
IPC0	0840	—	T1IP<2:0>			—	OC1IP<2:0>			—	IC1IP<2:0>			—	INT0IP<2:0>			4444
IPC1	0842	—	T2IP<2:0>			—	OC2IP<2:0>			—	IC2IP<2:0>			—	DMA0IP<2:0>			4444
IPC2	0844	—	U1RXIP<2:0>			—	SPI1IP<2:0>			—	SPI1EIP<2:0>			—	T3IP<2:0>			4444
IPC3	0846	—	—	—	—	—	DMA1IP<2:0>			—	AD1IP<2:0>			—	U1TXIP<2:0>			0444
IPC4	0848	—	CNIP<2:0>			—	CMIP<2:0>			—	MI2C1IP<2:0>			—	SI2C1IP<2:0>			4444
IPC5	084A	—	—	—	—	—	—	—	—	—	—	—	—	—	INT1IP<2:0>			0004
IPC6	084C	—	T4IP<2:0>			—	OC4IP<2:0>			—	OC3IP<2:0>			—	DMA2IP<2:0>			4444
IPC7	084E	—	U2TXIP<2:0>			—	U2RXIP<2:0>			—	INT2IP<2:0>			—	T5IP<2:0>			4444
IPC8	0850	—	—	—	—	—	C1RXIP<2:0>			—	SPI2IP<2:0>			—	SPI2EIP<2:0>			0444
IPC9	0852	—	—	—	—	—	IC4IP<2:0>			—	IC3IP<2:0>			—	DMA3IP<2:0>			0444
IPC12	0858	—	—	—	—	—	MI2C2IP<2:0>			—	SI2C2IP<2:0>			—	—	—	—	0440
IPC14	085C	—	—	—	—	—	QE11IP<2:0>			—	PSEMIP<2:0>			—	—	—	—	0440
IPC16	0860	—	CRCIP<2:0>			—	U2EIP<2:0>			—	U1EIP<2:0>			—	—	—	—	4440
IPC19	0866	—	—	—	—	—	—	—	—	—	CTMUIP<2:0>			—	—	—	—	0040
IPC23	086E	—	PWM2IP<2:0>			—	PWM1IP<2:0>			—	—	—	—	—	—	—	—	4400
IPC24	0870	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IP<2:0>			0004

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.4.1 PAGED MEMORY SCHEME

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X architecture extends the available Data Space through a paging scheme, which allows the available Data Space to be accessed using MOV instructions in a linear fashion for pre-modified and post-modified Effective Addresses (EA). The upper half of the base Data Space address is used in conjunction with the Data Space Page registers, the 10-bit Read Page register (DSRPAG) or the 9-bit Write Page register (DSWPAG), to form an Extended Data Space (EDS)

address or Program Space Visibility (PSV) address. The Data Space Page registers are located in the SFR space.

Construction of the EDS address is shown in Example 4-1. When DSRPAG<9> = 0 and the base address bit, EA<15> = 1, the DSRPAG<8:0> bits are concatenated onto EA<14:0> to form the 24-bit EDS read address. Similarly, when base address bit, EA<15> = 1, DSWPAG<8:0> are concatenated onto EA<14:0> to form the 24-bit EDS write address.

EXAMPLE 4-1: EXTENDED DATA SPACE (EDS) READ ADDRESS GENERATION

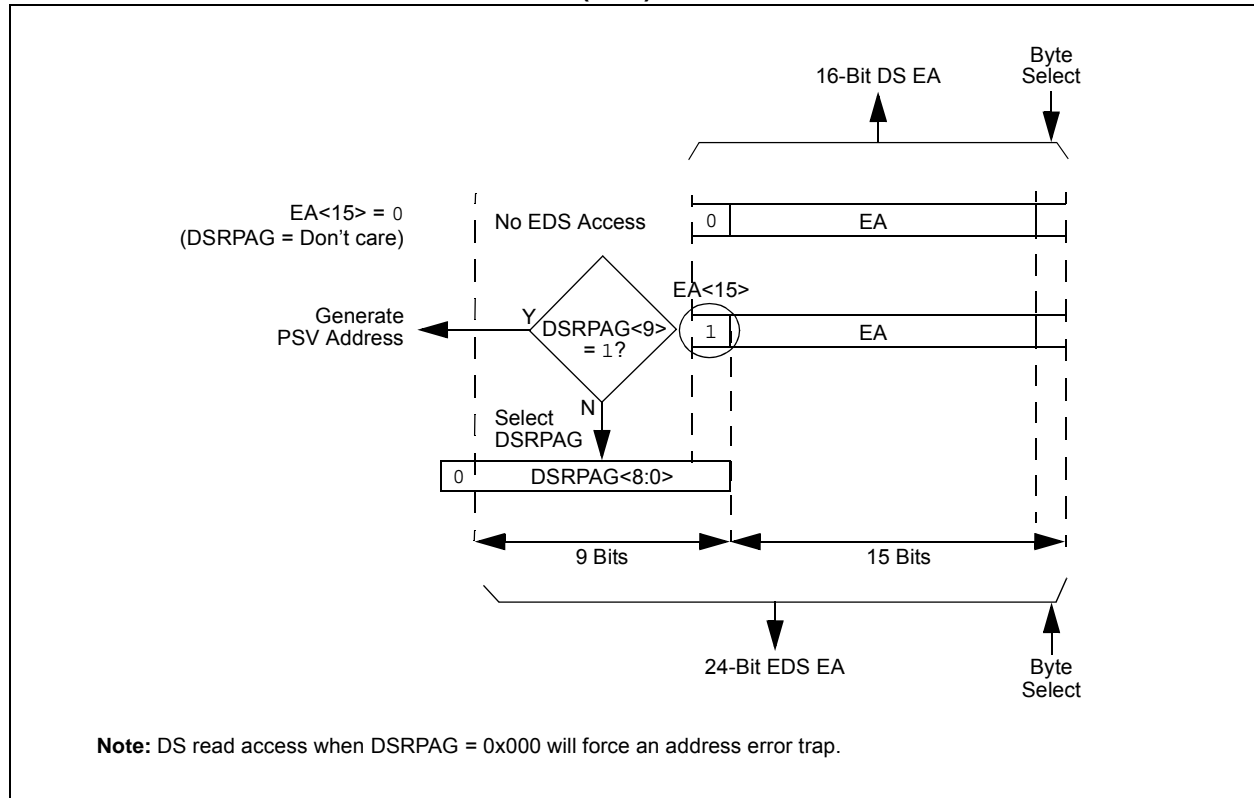


TABLE 11-1: SELECTABLE INPUT SOURCES (MAPS INPUT TO FUNCTION)

Input Name ⁽¹⁾	Function Name	Register	Configuration Bits
External Interrupt 1	INT1	RPINR0	INT1R<6:0>
External Interrupt 2	INT2	RPINR1	INT2R<6:0>
Timer2 External Clock	T2CK	RPINR3	T2CKR<6:0>
Input Capture 1	IC1	RPINR7	IC1R<6:0>
Input Capture 2	IC2	RPINR7	IC2R<6:0>
Input Capture 3	IC3	RPINR8	IC3R<6:0>
Input Capture 4	IC4	RPINR8	IC4R<6:0>
Output Compare Fault A	OCFA	RPINR11	OCFAR<6:0>
PWM Fault 1 ⁽³⁾	FLT1	RPINR12	FLT1R<6:0>
PWM Fault 2 ⁽³⁾	FLT2	RPINR12	FLT2R<6:0>
QE11 Phase A ⁽³⁾	QEA1	RPINR14	QEA1R<6:0>
QE11 Phase B ⁽³⁾	QEB1	RPINR14	QEB1R<6:0>
QE11 Index ⁽³⁾	INDX1	RPINR15	INDX1R<6:0>
QE11 Home ⁽³⁾	HOME1	RPINR15	HOM1R<6:0>
UART1 Receive	U1RX	RPINR18	U1RXR<6:0>
UART2 Receive	U2RX	RPINR19	U2RXR<6:0>
SPI2 Data Input	SDI2	RPINR22	SDI2R<6:0>
SPI2 Clock Input	SCK2	RPINR22	SCK2R<6:0>
SPI2 Slave Select	SS2	RPINR23	SS2R<6:0>
CAN1 Receive ⁽²⁾	C1RX	RPINR26	C1RXR<6:0>
PWM Sync Input 1 ⁽³⁾	SYNCI1	RPINR37	SYNCI1R<6:0>
PWM Dead-Time Compensation 1 ⁽³⁾	DTCMP1	RPINR38	DTCMP1R<6:0>
PWM Dead-Time Compensation 2 ⁽³⁾	DTCMP2	RPINR39	DTCMP2R<6:0>
PWM Dead-Time Compensation 3 ⁽³⁾	DTCMP3	RPINR39	DTCMP3R<6:0>

Note 1: Unless otherwise noted, all inputs use the Schmitt Trigger input buffers.

2: This input source is available on dsPIC33EPXXXGP/MC50X devices only.

3: This input source is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

REGISTER 11-13: RPINR23: PERIPHERAL PIN SELECT INPUT REGISTER 23

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SS2R<6:0>						
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-0 **SS2R<6:0>:** Assign SPI2 Slave Select ($\overline{SS2}$) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121

.

.

.

0000001 = Input tied to CMP1

0000000 = Input tied to Vss

**REGISTER 11-14: RPINR26: PERIPHERAL PIN SELECT INPUT REGISTER 26
(dsPIC33EPXXXGP/MC50X DEVICES ONLY)**

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	C1RXR<6:0>						
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-0 **C1RXR<6:0>:** Assign CAN1 RX Input (CRX1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121

.

.

.

0000001 = Input tied to CMP1

0000000 = Input tied to Vss

NOTES:

REGISTER 19-1: I2CxCON: I2Cx CONTROL REGISTER (CONTINUED)

- bit 6 **STREN:** SCLx Clock Stretch Enable bit (when operating as I²C slave)
Used in conjunction with the SCLREL bit.
1 = Enables software or receives clock stretching
0 = Disables software or receives clock stretching
- bit 5 **ACKDT:** Acknowledge Data bit (when operating as I²C master, applicable during master receive)
Value that is transmitted when the software initiates an Acknowledge sequence.
1 = Sends NACK during Acknowledge
0 = Sends ACK during Acknowledge
- bit 4 **ACKEN:** Acknowledge Sequence Enable bit
(when operating as I²C master, applicable during master receive)
1 = Initiates Acknowledge sequence on SDAx and SCLx pins and transmits ACKDT data bit. Hardware is clear at the end of the master Acknowledge sequence.
0 = Acknowledge sequence is not in progress
- bit 3 **RCEN:** Receive Enable bit (when operating as I²C master)
1 = Enables Receive mode for I²C. Hardware is clear at the end of the eighth bit of the master receive data byte.
0 = Receive sequence is not in progress
- bit 2 **PEN:** Stop Condition Enable bit (when operating as I²C master)
1 = Initiates Stop condition on SDAx and SCLx pins. Hardware is clear at the end of the master Stop sequence.
0 = Stop condition is not in progress
- bit 1 **RSEN:** Repeated Start Condition Enable bit (when operating as I²C master)
1 = Initiates Repeated Start condition on SDAx and SCLx pins. Hardware is clear at the end of the master Repeated Start sequence.
0 = Repeated Start condition is not in progress
- bit 0 **SEN:** Start Condition Enable bit (when operating as I²C master)
1 = Initiates Start condition on SDAx and SCLx pins. Hardware is clear at the end of the master Start sequence.
0 = Start condition is not in progress

Note 1: When performing master operations, ensure that the IPMIEN bit is set to '0'.

REGISTER 21-22: CxRXFUL1: ECANx RECEIVE BUFFER FULL REGISTER 1

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL15	RXFUL14	RXFUL13	RXFUL12	RXFUL11	RXFUL10	RXFUL9	RXFUL8
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL7	RXFUL6	RXFUL5	RXFUL4	RXFUL3	RXFUL2	RXFUL1	RXFUL0
bit 7							bit 0

Legend:	C = Writable bit, but only '0' can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **RXFUL<15:0>:** Receive Buffer n Full bits
 1 = Buffer is full (set by module)
 0 = Buffer is empty (cleared by user software)

REGISTER 21-23: CxRXFUL2: ECANx RECEIVE BUFFER FULL REGISTER 2

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL31	RXFUL30	RXFUL29	RXFUL28	RXFUL27	RXFUL26	RXFUL25	RXFUL24
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL23	RXFUL22	RXFUL21	RXFUL20	RXFUL19	RXFUL18	RXFUL17	RXFUL16
bit 7							bit 0

Legend:	C = Writable bit, but only '0' can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **RXFUL<31:16>:** Receive Buffer n Full bits
 1 = Buffer is full (set by module)
 0 = Buffer is empty (cleared by user software)

The diagram illustrates the internal architecture of the C4 module. It features two 2-to-1 multiplexers at the input. The first multiplexer selects between $OA1/AN3$ (input 01) and $OA3/AN6$ (input 11) to produce $VIN-$. Its other input is $C4IN1-$ (input 00), which is also connected to the $CCH<1:0>$ (CM4CON<1:0>) control signal. The second multiplexer selects between $C4IN1+$ (input 1) and $CVREFIN$ (input 0) to produce $VIN+$. Its other input is $CREF$ (CMxCON<4>). The $VIN-$ and $VIN+$ signals are fed into the non-inverting (+) and inverting (-) inputs of the $CMP4$ comparator. The output of the comparator is processed by a **Blanking Function** (referenced to Figure 25-4) and then a **Digital Filter** (referenced to Figure 25-5). The final output of the digital filter is $C4OUT$, which is also connected to a **Trigger Output**.

The diagram illustrates the internal architecture of the CVR module. It features a 16-to-1 multiplexer (MUX) at its core. The MUX's inputs are derived from a 16-step resistor ladder. The top of this ladder is connected to CVRSS, which is selected between VREF+ and AVDD via a switch controlled by CVRSS = 1(1) and CVRSS = 0. The bottom of the ladder is connected to CVRR and AVSS through an 8R resistor network. The MUX is controlled by bits CVR3, CVR2, CVR1, and CVR0 from the CVRCON register. The MUX output is connected to CVREFIN and also passes through a switch controlled by CVR10E (CVRCON<6>) to produce CVREF10. Additionally, the MUX output is connected to a divider network between AVDD and AVSS, controlled by CVR20E (CVRCON<14>), to produce CVREF20(2). The CVRCON register also includes a VREFSEL (CVRCON<10>) bit that selects between CVREFIN and CVREF20(2) for the final CVREF output.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles ⁽²⁾	Status Flags Affected
46	MOV	MOV <i>f</i> , <i>Wn</i>	Move <i>f</i> to <i>Wn</i>	1	1	None
		MOV <i>f</i>	Move <i>f</i> to <i>f</i>	1	1	None
		MOV <i>f</i> , WREG	Move <i>f</i> to WREG	1	1	None
		MOV #lit16, <i>Wn</i>	Move 16-bit literal to <i>Wn</i>	1	1	None
		MOV.b #lit8, <i>Wn</i>	Move 8-bit literal to <i>Wn</i>	1	1	None
		MOV <i>Wn</i> , <i>f</i>	Move <i>Wn</i> to <i>f</i>	1	1	None
		MOV <i>Wso</i> , <i>Wdo</i>	Move <i>Ws</i> to <i>Wd</i>	1	1	None
		MOV WREG, <i>f</i>	Move WREG to <i>f</i>	1	1	None
		MOV.D <i>Wns</i> , <i>Wd</i>	Move Double from <i>W(ns):W(ns + 1)</i> to <i>Wd</i>	1	2	None
		MOV.D <i>Ws</i> , <i>Wnd</i>	Move Double from <i>Ws</i> to <i>W(nd + 1):W(nd)</i>	1	2	None
47	MOVPG	MOVPG #lit10, DSRPAG	Move 10-bit literal to DSRPAG	1	1	None
		MOVPG #lit9, DSWPAG	Move 9-bit literal to DSWPAG	1	1	None
		MOVPG #lit8, TBLPAG	Move 8-bit literal to TBLPAG	1	1	None
		MOVPG <i>Ws</i> , DSRPAG	Move <i>Ws</i> <9:0> to DSRPAG	1	1	None
		MOVPG <i>Ws</i> , DSWPAG	Move <i>Ws</i> <8:0> to DSWPAG	1	1	None
		MOVPG <i>Ws</i> , TBLPAG	Move <i>Ws</i> <7:0> to TBLPAG	1	1	None
48	MOVSAC	MOVSAC <i>Acc</i> , <i>Wx</i> , <i>Wxd</i> , <i>Wy</i> , <i>Wyd</i> , AWB ⁽¹⁾	Prefetch and store accumulator	1	1	None
49	MPY	MPY <i>Wm</i> * <i>Wn</i> , <i>Acc</i> , <i>Wx</i> , <i>Wxd</i> , <i>Wy</i> , <i>Wyd</i> ⁽¹⁾	Multiply <i>Wm</i> by <i>Wn</i> to Accumulator	1	1	OA,OB,OAB,SA,SB,SAB
		MPY <i>Wm</i> * <i>Wm</i> , <i>Acc</i> , <i>Wx</i> , <i>Wxd</i> , <i>Wy</i> , <i>Wyd</i> ⁽¹⁾	Square <i>Wm</i> to Accumulator	1	1	OA,OB,OAB,SA,SB,SAB
50	MPY.N	MPY.N <i>Wm</i> * <i>Wn</i> , <i>Acc</i> , <i>Wx</i> , <i>Wxd</i> , <i>Wy</i> , <i>Wyd</i> ⁽¹⁾	-(Multiply <i>Wm</i> by <i>Wn</i>) to Accumulator	1	1	None
51	MSC	MSC <i>Wm</i> * <i>Wm</i> , <i>Acc</i> , <i>Wx</i> , <i>Wxd</i> , <i>Wy</i> , <i>Wyd</i> , AWB ⁽¹⁾	Multiply and Subtract from Accumulator	1	1	OA,OB,OAB,SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DI60a	I _{ICL}	Input Low Injection Current	0	—	-5 ^(4,7)	mA	All pins except V _{DD} , V _{SS} , AV _{DD} , AV _{SS} , MCLR, VCAP and RB7
DI60b	I _{ICH}	Input High Injection Current	0	—	+5 ^(5,6,7)	mA	All pins except V _{DD} , V _{SS} , AV _{DD} , AV _{SS} , MCLR, VCAP, RB7 and all 5V tolerant pins ⁽⁶⁾
DI60c	ΣI_{ICT}	Total Input Injection Current (sum of all I/O and control pins)	-20 ⁽⁸⁾	—	+20 ⁽⁸⁾	mA	Absolute instantaneous sum of all \pm input injection currents from all I/O pins ($ I_{ICL} + I_{ICH} $) $\leq \Sigma I_{ICT}$

- Note 1:** The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.
- 2:** Negative current is defined as current sourced by the pin.
- 3:** See the “Pin Diagrams” section for the 5V tolerant I/O pins.
- 4:** V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.
- 5:** Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.
- 6:** Digital 5V tolerant pins cannot tolerate any “positive” input injection current from input sources > 5.5V.
- 7:** Non-zero injection currents can affect the ADC results by approximately 4-6 counts.
- 8:** Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

**TABLE 30-38: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0)
TIMING REQUIREMENTS**

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units	Conditions
SP70	FscP	Maximum SCK2 Input Frequency	—	—	Lesser of Fp or 11	MHz	(Note 3)
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	Tsch2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	Tsch2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2} \downarrow$ to SCK2 \uparrow or SCK2 \downarrow Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2} \uparrow$ to SDO2 Output High-Impedance	10	—	50	ns	(Note 4)
SP52	Tsch2ssH, TscL2ssH	$\overline{SS2} \uparrow$ after SCK2 Edge	1.5 Tcy + 40	—	—	ns	(Note 4)
SP60	TssL2doV	SDO2 Data Output Valid after $\overline{SS2}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-50: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param. No.	Symbol	Characteristic ⁽³⁾		Min.	Max.	Units	Conditions
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	μs	
			400 kHz mode	1.3	—	μs	
			1 MHz mode ⁽¹⁾	0.5	—	μs	
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			1 MHz mode ⁽¹⁾	0.5	—	μs	
IS20	TF:SCL	SDA _x and SCL _x Fall Time	100 kHz mode	—	300	ns	Cb is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 Cb	300	ns	
			1 MHz mode ⁽¹⁾	—	100	ns	
IS21	TR:SCL	SDA _x and SCL _x Rise Time	100 kHz mode	—	1000	ns	Cb is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 Cb	300	ns	
			1 MHz mode ⁽¹⁾	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode ⁽¹⁾	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	μs	
			400 kHz mode	0	0.9	μs	
			1 MHz mode ⁽¹⁾	0	0.3	μs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	μs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	μs	
			1 MHz mode ⁽¹⁾	0.25	—	μs	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	μs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	μs	
			1 MHz mode ⁽¹⁾	0.25	—	μs	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	μs	
			400 kHz mode	0.6	—	μs	
			1 MHz mode ⁽¹⁾	0.6	—	μs	
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4	—	μs	
			400 kHz mode	0.6	—	μs	
			1 MHz mode ⁽¹⁾	0.25	—	μs	
IS40	TAA:SCL	Output Valid From Clock	100 kHz mode	0	3500	ns	
			400 kHz mode	0	1000	ns	
			1 MHz mode ⁽¹⁾	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode ⁽¹⁾	0.5	—	μs	
IS50	CB	Bus Capacitive Loading		—	400	pF	
IS51	TPGD	Pulse Gobbler Delay		65	390	ns	(Note 2)

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

2: Typical value for this parameter is 130 ns.

3: These parameters are characterized, but not tested in manufacturing.

TABLE 30-58: ADC MODULE SPECIFICATIONS (12-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) ⁽¹⁾ Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
ADC Accuracy (12-Bit Mode)							
AD20a	Nr	Resolution	12 Data Bits			bits	
AD21a	INL	Integral Nonlinearity	-2.5	—	2.5	LSb	-40°C ≤ TA ≤ +85°C (Note 2)
			-5.5	—	5.5	LSb	+85°C < TA ≤ +125°C (Note 2)
AD22a	DNL	Differential Nonlinearity	-1	—	1	LSb	-40°C ≤ TA ≤ +85°C (Note 2)
			-1	—	1	LSb	+85°C < TA ≤ +125°C (Note 2)
AD23a	GERR	Gain Error ⁽³⁾	-10	—	10	LSb	-40°C ≤ TA ≤ +85°C (Note 2)
			-10	—	10	LSb	+85°C < TA ≤ +125°C (Note 2)
AD24a	EOFF	Offset Error	-5	—	5	LSb	-40°C ≤ TA ≤ +85°C (Note 2)
			-5	—	5	LSb	+85°C < TA ≤ +125°C (Note 2)
AD25a	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance (12-Bit Mode)							
AD30a	THD	Total Harmonic Distortion ⁽³⁾	—	75	—	dB	
AD31a	SINAD	Signal to Noise and Distortion ⁽³⁾	—	68	—	dB	
AD32a	SFDR	Spurious Free Dynamic Range ⁽³⁾	—	80	—	dB	
AD33a	FNYQ	Input Signal Bandwidth ⁽³⁾	—	250	—	kHz	
AD34a	ENOB	Effective Number of Bits ⁽³⁾	11.09	11.3	—	bits	

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: For all accuracy specifications, VINL = AVSS = VREFL = 0V and AVDD = VREFH = 3.6V.

3: Parameters are characterized but not tested in manufacturing.

31.0 HIGH-TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 30.0 “Electrical Characteristics”** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter DC10 in **Section 30.0 “Electrical Characteristics”** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X high-temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings⁽¹⁾

Ambient temperature under bias ⁽²⁾	-40°C to +150°C
Storage temperature	-65°C to +160°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to VSS ⁽³⁾	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD < 3.0V ⁽³⁾	-0.3V to 3.6V
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 3.0V ⁽³⁾	-0.3V to 5.5V
Maximum current out of VSS pin	60 mA
Maximum current into VDD pin ⁽⁴⁾	60 mA
Maximum junction temperature	+155°C
Maximum current sourced/sunk by any 4x I/O pin	10 mA
Maximum current sourced/sunk by any 8x I/O pin	15 mA
Maximum current sunk by all ports combined	70 mA
Maximum current sourced by all ports combined ⁽⁴⁾	70 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

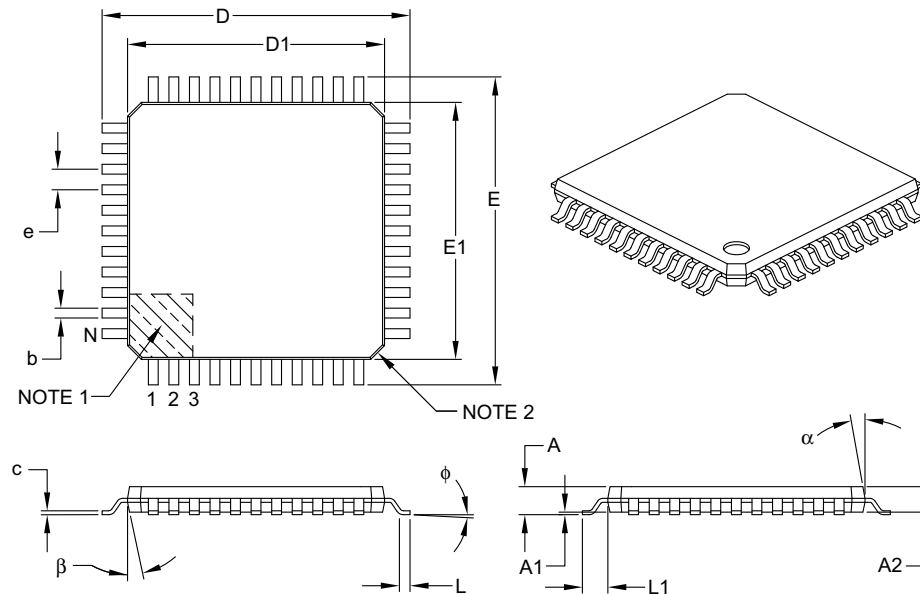
2: AEC-Q100 reliability testing for devices intended to operate at +150°C is 1,000 hours. Any design in which the total operating time from +125°C to +150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

3: Refer to the “**Pin Diagrams**” section for 5V tolerant pins.

4: Maximum allowable current is a function of device maximum power dissipation (see Table 31-2).

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	44		
Lead Pitch	e	0.80 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Chamfers at corners are optional; size may vary.
- Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B